

TECHNIQUES FOR PROVIDING EMI SHIELDING WITHIN
A CIRCUIT BOARD COMPONENT

ABSTRACT OF THE DISCLOSURE

5 A circuit board component includes a substrate having non-conductive material and conductive material supported by the non-conductive material. The conductive material defines a circuit board interface, a die interface, a heat spreader interface, and (iv) a set of connections which interconnects the circuit board interface, the die interface and the heat spreader interface. The component further includes a die coupled to the die
10 interface. The die includes integrated circuitry which is configured to electrically communicate with a circuit board when the circuit board couples to the circuit board interface. The component further includes a heat spreader coupled to the heat spreader interface. The heat spreader is configured to dissipate heat from the die. The heat spreader in combination with the heat spreader interface forms an electromagnetic
15 interference shield when a portion of the circuit board interface connects to a ground reference of the circuit board.